

# N-Channel 60 V (D-S) MOSFET

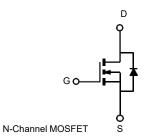
PRODUCT SUMMARY				
V <sub>DS</sub>	60	V		
$R_{DS(on)}V_{GS} = 10 V$	4	mΩ		
I <sub>D</sub>	150	Α		
Configuration	Single			

### **FEATURES**

- TrenchFET® power MOSFET
- Package with low thermal resistance
- 100 %  $R_{\mbox{\scriptsize g}}$  and UIS tested







ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unless	otherwise noted)		
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	60	.,
Gate-Source Voltage		V <sub>GS</sub>	± 20	V
Continuous Drain Current	T <sub>C</sub> = 25 °C <sup>a</sup>	- I <sub>D</sub> -	150	
	T <sub>C</sub> = 125 °C		65	
Continuous Source Current (Diode Conduction) <sup>a</sup>		Is	120	A
Pulsed Drain Current b		I <sub>DM</sub>	350	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	65	
Single Pulse Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	211	mJ
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	Pn	220	W
	T <sub>C</sub> = 125 °C	r <sub>D</sub>	70	] vv
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount c	R <sub>thJA</sub>	40	°C/W		
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.65	C/VV		

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR4 material).



PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static	<u>'</u>	,					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		60	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA			4.0	\ \
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \geq 5 \ V$	120	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A	-	6	-	mΩ
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	12	-	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	15	-	
Forward Transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		-	94	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	-	7000	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 25 V, f = 1 MHz	-	-	715	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	-	360	
Total Gate Charge <sup>c</sup>	Qg			-	96	145	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 75 \text{ A}$	-	24	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>				27	-	]
Gate Resistance	Rg	f = 1 MHz		0.3	1	1.7	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	16	24	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_L = 0.4 \Omega$ $I_D \cong 75 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		-	14	21	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	34	51	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	9	14	
Source-Drain Diode Ratings and Chara	cteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	450	Α
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 75 A, V <sub>GS</sub> = 0		_	0.9	1.5	V

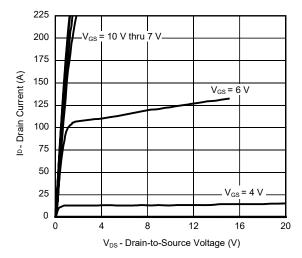
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$  b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

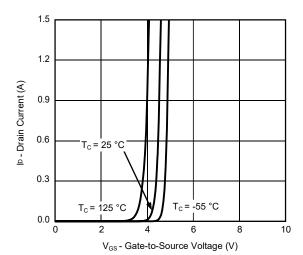
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



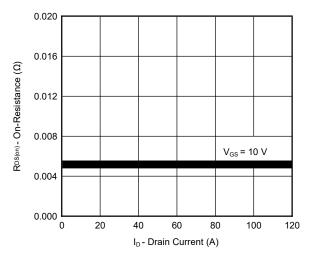
## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



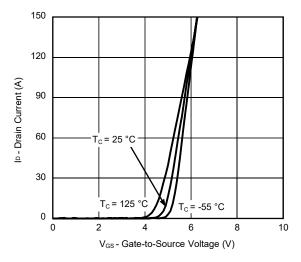




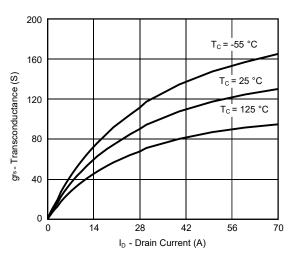
**Transfer Characteristics** 



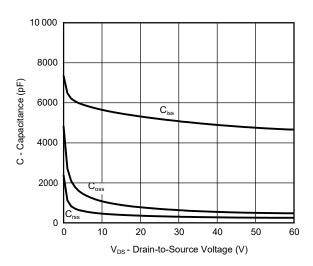
On-Resistance vs. Drain Current



**Transfer Characteristics** 



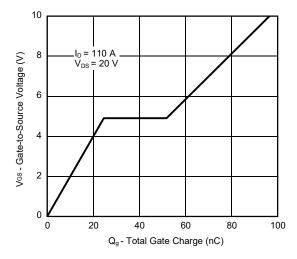
Transconductance



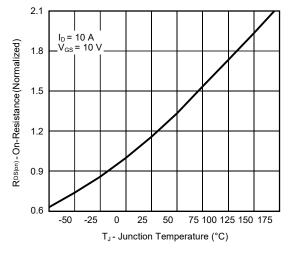
Capacitance



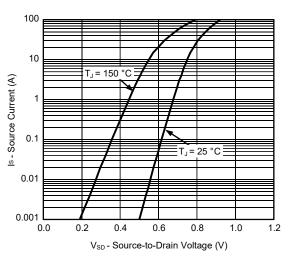
### TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



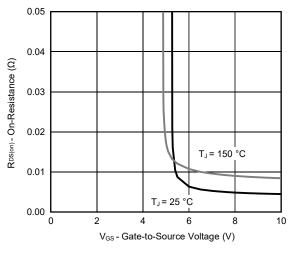
**Gate Charge** 



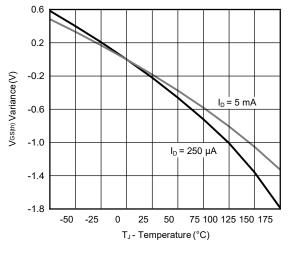
On-Resistance vs. Junction Temperature



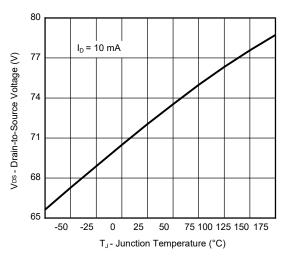
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



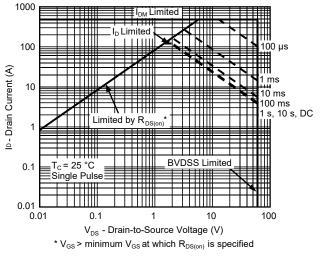
Threshold Voltage



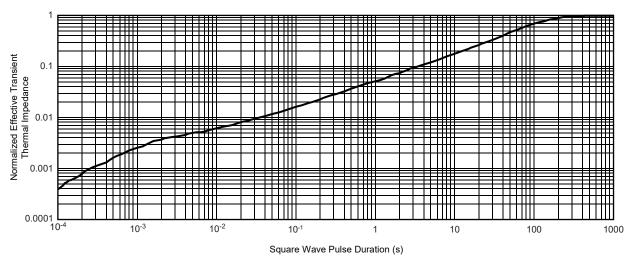
Drain Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



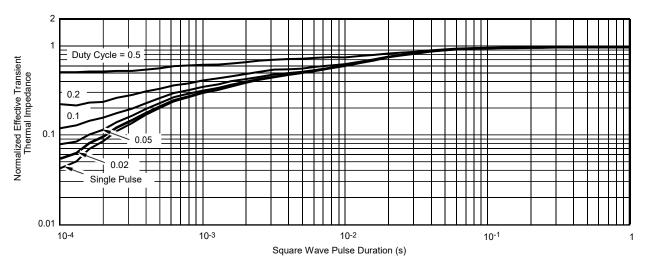
#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

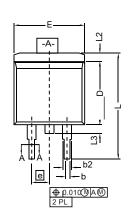
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

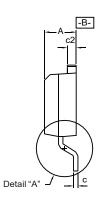
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

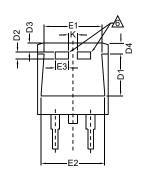


**MILLIMETERS** 

# **TO-263 (D<sup>2</sup>PAK): 3-LEAD**



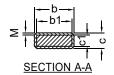




**INCHES** 



#### **DETAIL A (ROTATED 90°)**



#### Notes

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by  $\;$  max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. \*: Thin lead is for SUB, SYB.
  Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

  6. This feature is for thick lead.

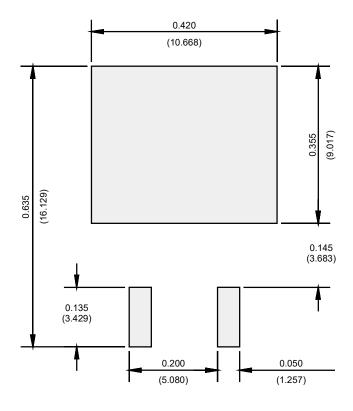
1						
DIM.		MIN.	MAX.	MIN.	MAX.	
A		0.160	0.190	4.064	4.826	
b		0.020	0.039	0.508	0.990	
b1		0.020	0.035	0.508	0.889	
b2		0.045	0.055	1.143	1.397	
С*	Thin lead	0.013	0.018	0.330	0.457	
	Thick lead	0.023	0.028	0.584	0.711	
c1	Thin lead	0.013	0.017	0.330	0.431	
	Thick lead	0.023	0.027	0.584	0.685	
c2		0.045	0.055	1.143	1.397	
D		0.340	0.380	8.636	9.652	
D1		0.220	0.240	5.588	6.096	
D2		0.038	0.042	0.965	1.067	
D3		0.045	0.055	1.143	1.397	
D4		0.044	0.052	1.118	1.321	
E		0.380	0.410	9.652	10.414	
E1		0.245	-	6.223	-	
E2		0.355	0.375	9.017	9.525	
E3		0.072	0.078	1.829	1.981	
е		0.100	BSC	2.54 BSC		
K		0.045	0.055	1.143	1.397	
L		0.575	0.625	14.605	15.875	
L1		0.090	0.110	2.286	2.794	
L2		0.040	0.055	1.016	1.397	
L3		0.050	0.070	1.270	1.778	
L4		0.010	BSC	0.254	BSC	
	М	-	0.002	-	0.050	
ECN: T13 0707 Pov. K. 30 Sop. 13						

ECN: T13-0707-Rev. K, 30-Sep-13

DWG: 5843



## RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP NTMC083NP10M5L BXP7N65D BXP4N65F AOL1454G
WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13
SLF10N65ABV2 BSO203SP BSO211P IPA60R230P6